# Old Company Name in Catalogs and Other Documents

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Renesas Electronics website: http://www.renesas.com

April 1<sup>st</sup>, 2010 Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (http://www.renesas.com)

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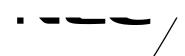


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#### **DATA SHEET**



# MOS FIELD EFFECT TRANSISTOR NP80N055MDG, NP80N055PDG

# SWITCHING N-CHANNEL POWER MOS FET

#### **DESCRIPTION**

The NP80N055MDG, NP80N055NDG, and NP80N055PDG are N-channel MOS Field Effect Transistors designed for high current switching applications.

#### **ORDERING INFORMATION**

PART NUMBER	LEAD PLATING	PACKING	PACKAGE
NP80N055MDG-S18-AY Note		Tube	TO-220 (MP-25K) typ. 1.9 g
NP80N055NDG-S18-AY Note		50 p/tube	TO-262 (MP-25SK) typ. 1.8 g
NP80N055PDG-E1B-AY Note	Pure Sn (Tin)	Tape	
NP80N055PDG-E2B-AY Note		1000 p/reel	TO-263 (MP-25ZP) typ. 1.5 g

Note Pb-free (This product does not contain Pb in the external electrode.)

FEATURES (TO-220)

- Logic level
- Super low on-state resistance
  - NP80N055MDG, NP80N055NDG

 $R_{DS(on)1} = 6.9 \text{ m}\Omega \text{ MAX.} \text{ (Vgs} = 10 \text{ V, I}_D = 40 \text{ A)}$ 

 $R_{DS(on)2} = 11.2 \text{ m}\Omega \text{ MAX.} (V_{GS} = 4.5 \text{ V}, I_D = 35 \text{ A})$ 

- NP80N055PDG

 $R_{DS(on)1}$  = 6.6  $m\Omega$  MAX. (Vgs = 10 V, Ip = 40 A)

 $R_{DS(on)2}$  = 10.9  $m\Omega$  MAX. (Vgs = 4.5 V, Ip = 35 A)

• High current rating

 $I_{D(DC)} = \pm 80 A$ 

• Low input capacitance

Ciss = 4600 pF TYP.

• Designed for automotive application and AEC-Q101 qualified



(TO-262)



(TO-263)



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#### ABSOLUTE MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Drain to Source Voltage (VGS = 0 V)	VDSS	55	V
Gate to Source Voltage (VDS = 0 V)	Vgss	±20	V
Drain Current (DC) (Tc = 25°C)	I <sub>D(DC)</sub>	±80	Α
Drain Current (pulse) Note1	D(pulse)	±200	Α
Total Power Dissipation (Tc = 25°C)	P <sub>T1</sub>	115	W
Total Power Dissipation (T <sub>A</sub> = 25°C)	P <sub>T2</sub>	1.8	W
Channel Temperature	Tch	175	°C
Storage Temperature	Tstg	-55 to +175	°C
Repetitive Avalanche Current Note2	Iar	33	Α
Repetitive Avalanche Energy Note2	Ear	111	mJ

**Notes 1.** PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1%

**2.** Tch  $\leq$  150°C, Rg = 25  $\Omega$ 

#### THERMAL RESISTANCE

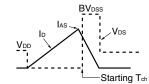
Channel to Case Thermal Resistance	Rth(ch-C)	1.30	°C/W
Channel to Ambient Thermal Resistance	Rth(ch-A)	83.3	°C/W

#### **ELECTRICAL CHARACTERISTICS (TA = 25°C)**

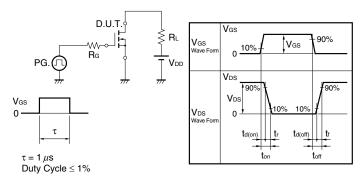
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = 55 V, V <sub>GS</sub> = 0 V			1	μA
Gate Leakage Current	Igss	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
Gate to Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.4		2.5	V
Forward Transfer Admittance Note	yfs	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 35 A	25	64		S
Drain to Source On-state Resistance Note	RDS(on)1	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 40 A NP80N055MDG, NP80N055NDG		5.4	6.9	mΩ
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 40 A NP80N055PDG		4.8	6.6	mΩ
	RDS(on)2	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 35 A NP80N055MDG, NP80N055NDG		6.3	11.2	mΩ
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 35 A NP80N055PDG		5.9	10.9	mΩ
Input Capacitance	Ciss	V <sub>DS</sub> = 25 V,		4600	6900	pF
Output Capacitance	Coss	$V_{GS} = 0 V$ ,		390	590	pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		240	430	pF
Turn-on Delay Time	td(on)	$V_{DD} = 28 \text{ V}, I_D = 40 \text{ A},$		17	37	ns
Rise Time	tr	V <sub>GS</sub> = 10 V,		13	33	ns
Turn-off Delay Time	t <sub>d(off)</sub>	$R_G = 0 \Omega$		77	154	ns
Fall Time	tr			7	18	ns
Total Gate Charge	Q <sub>G</sub>	V <sub>DD</sub> = 44 V,		90	135	nC
Gate to Source Charge	Qgs	V <sub>GS</sub> = 10 V,		13		nC
Gate to Drain Charge	Q <sub>GD</sub>	I <sub>D</sub> = 80 A		26		nC
Body Diode Forward Voltage Note	V <sub>F(S-D)</sub>	I <sub>F</sub> = 80 A, V <sub>GS</sub> = 0 V		0.95	1.5	V
Reverse Recovery Time	trr	I <sub>F</sub> = 80 A, V <sub>GS</sub> = 0 V,		38		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/ <i>μ</i> s		45		nC

Note Pulsed test

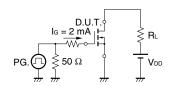
#### TEST CIRCUIT 1 AVALANCHE CAPABILITY



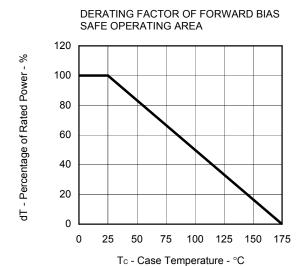
#### TEST CIRCUIT 2 SWITCHING TIME



#### **TEST CIRCUIT 3 GATE CHARGE**



#### TYPICAL CHARACTERISTICS (TA = 25°C)



# CASE TEMPERATURE 125 100 75

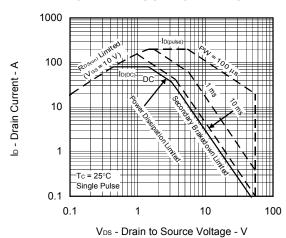
TOTAL POWER DISSIPATION vs.

0 25 50 75 100 125 150

Tc - Case Temperature - °C

175

#### FORWARD BIAS SAFE OPERATING AREA

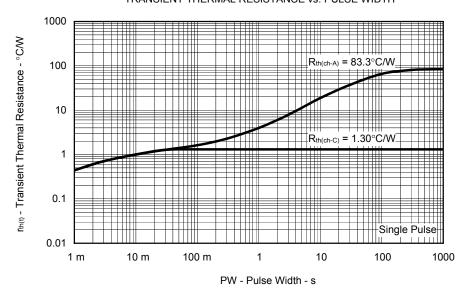


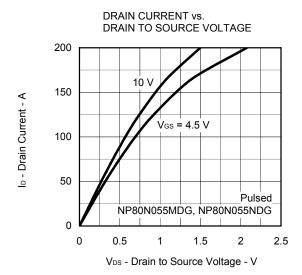
#### TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

P<sub>T</sub> - Total Power Dissipation - W

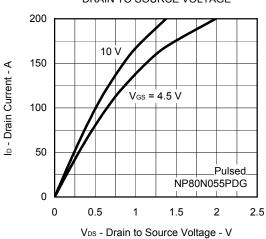
50

25

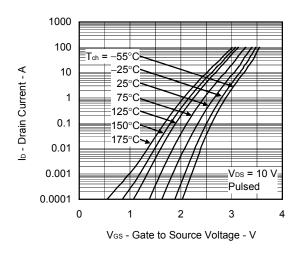




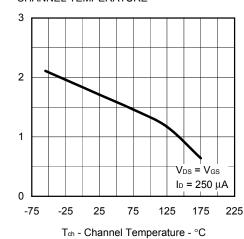
## DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



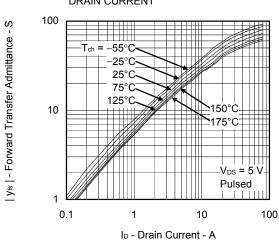
#### FORWARD TRANSFER CHARACTERISTICS



GATE TO SOURCE THRESHOLD VOLTAGE vs. CHANNEL TEMPERATURE



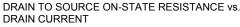
# FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

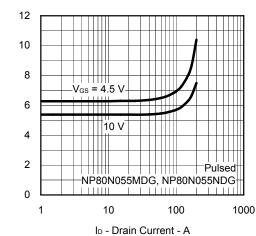


Vos(th) - Gate to Source Threshold Voltage - V

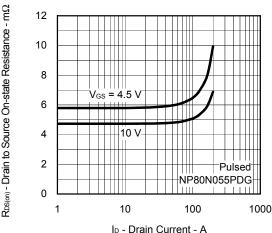
 $R_{DS(m)}$  - Drain to Source On-state Resistance -  $m\Omega$ 

R<sub>DS(on)</sub> - Drain to Source On-state Resistance - mΩ

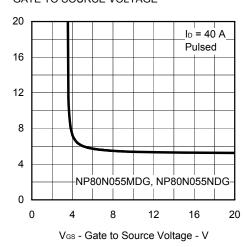




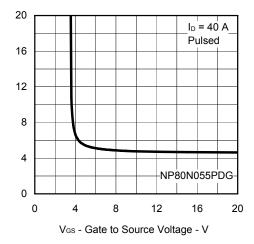
### DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



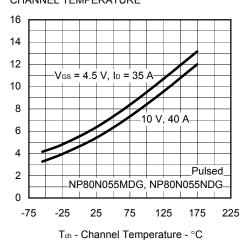
# DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



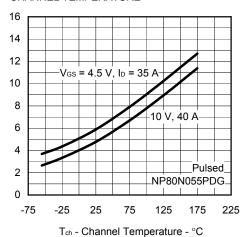
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE

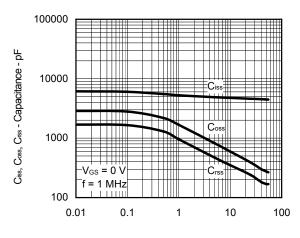


R<sub>DS(ση)</sub> - Drain to Source On-state Resistance - mΩ

R<sub>DS(on)</sub> - Drain to Source On-state Resistance - mΩ

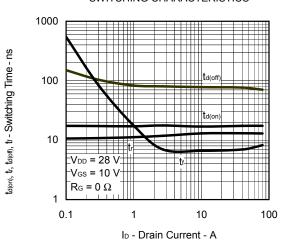
R<sub>DS(σ1)</sub> - Drain to Source On-state Resistance - mΩ

#### CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE

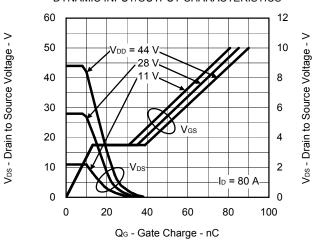


V<sub>DS</sub> - Drain to Source Voltage - V

SWITCHING CHARACTERISTICS

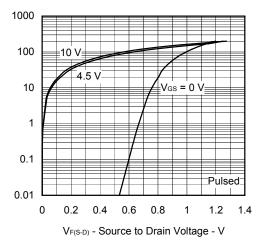


DYNAMIC INPUT/OUTPUT CHARACTERISTICS

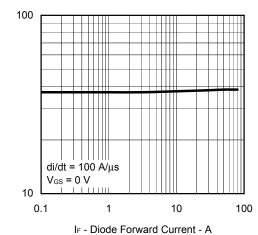


IF - Diode Forward Current - A

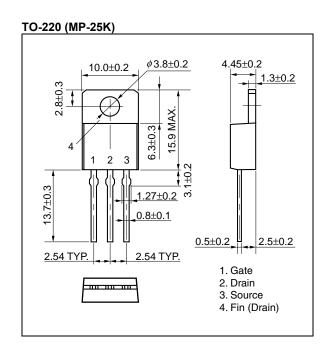
SOURCE TO DRAIN DIODE FORWARD VOLTAGE

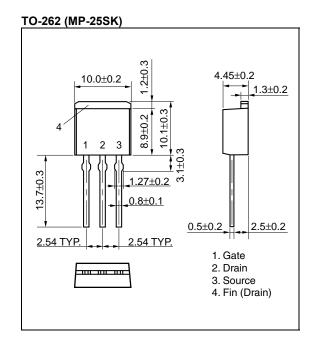


REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT

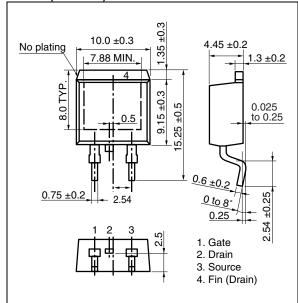


#### PACKAGE DRAWINGS (Unit: mm)

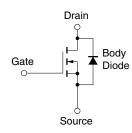




#### TO-263 (MP-25ZP)



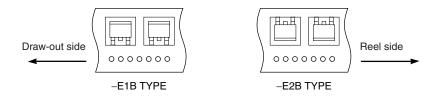
#### **EQUIVALENT CIRCUIT**



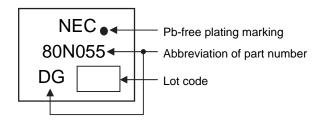
**Remark** Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

#### **TAPE INFORMATION (NP80N055PDG)**

There are two types (-E1B, -E2B) of taping depending on the direction of the device.



#### MARKING INFORMATION



#### RECOMMENDED SOLDERING CONDITIONS

These products should be soldered and mounted under the following recommended conditions.

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For technical information, see the following website.

Semiconductor Device Mount Manual (http://www.necel.com/pkg/en/mount/index.html)

Soldering Method	Soldering Conditions	Recommended Condition Symbol
Infrared reflow NP80N055PDG	Maximum temperature (Package's surface temperature): 260°C or below Time at maximum temperature: 10 seconds or less Time of temperature higher than 220°C: 60 seconds or less Preheating time at 160 to 180°C: 60 to 120 seconds Maximum number of reflow processes: 3 times Maximum chlorine content of rosin flux (percentage mass): 0.2% or less	IR60-00-3
Wave soldering NP80N055MDG, NP80N055NDG	Maximum temperature (Solder temperature): 260°C or below Time: 10 seconds or less Maximum chlorine content of rosin flux: 0.2% (wt.) or less	THDWS
Partial heating NP80N055MDG, NP80N055NDG, NP80N055PDG	Maximum temperature (Pin temperature): 350°C or below Time (per side of the device): 3 seconds or less Maximum chlorine content of rosin flux: 0.2% (wt.) or less	P350

Caution Do not use different soldering methods together (except for partial heating).

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